

PRODUCT SPECIFICATION

6252M-PUB

Wi-Fi Dual-band 2T2R 11ax +Bluetooth

Combo Module

Version:v1.8

Customer: _____

Customer P/N: _____

Signature: _____

Date: _____

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6252M-PUB Module Datasheet

Ordering Information	Part NO.	Description
	FG6252MPUB-00	RTL8852BE-CG, a/b/g/n/ac/ax, Wi-Fi+BT5.2, 2T2R, 22X30mm, PCIE+USB, PCB Version V1.0



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Revision History

[illegible]

1. General Description

1.1 Introduction

The fn-link6252M-PUB is a highly integrated single-chip that support 2-stream 802.11ax solutions with Multi-user MIMO (Multiple-Input, Multiple-Output) with Wireless LAN (WLAN) PCI Express network interface controller with integrated Bluetooth 5 USB interface controller. It combines a WLAN MAC, a 2T2R capable WLAN baseband, and RF in a single chip. The RTL8852BE provides a complete solution for a high-performance integrated wireless and Bluetooth device.

1.2 Description

Model Name	6252M-PUB
Product Description	Support Wi-Fi/Bluetooth functionalities
Dimension	L x W x H: 22x 30x 2.2 (typical) mm
Wi-Fi Interface	Support PCIe
BT Interface	USB
OS supported	Android /Linux/ Windows
Operating temperature	0°C to 70°C
Storage temperature	-55°C to 85°C

2. Features

General Features

- IEEE 802.11a/b/g/n/ac/ax compatible WLAN
- Supports 20/40MHz at 2.4GHz and supports 20/40/80MHz at 5GHz.
- Supports 802.11ac 2x2, Wave-2 compliant with RX MU-MIMO
- Complete 802.11n MIMO solution for 2.4GHz and 5GHz band
- 802.1X (EAPTLS, TTLS, PEAP, LEAP.EAP-FAST)), (EAP-SIM, EAP-AKA)-with OS supports
- IEEE 802.11i(WPA, WPA2, WPA3).Open,shared key, and pair-wise key authentication services
- Support S3/S4 AES/TKIP group key update

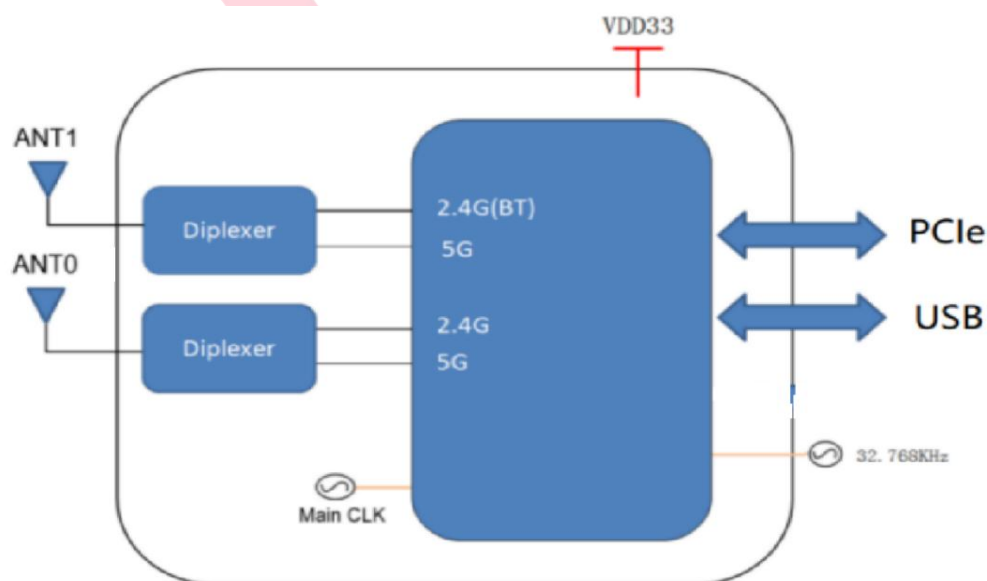
WLAN Interface

- Supports low power PCIe(Base Specification Revision 1.1) interface for WLAN and USB(2.0 FS-mode)

Bluetooth Features

- Supports Bluetooth 5.2 system
- Compatible with Bluetooth v2.1+EDR
- Dual Mode support: Simultaneous LE and BR/EDR
- Enhanced BT/Wi-Fi Coexistence Control to improve transmission quality in different profiles
- Supports Bluetooth for class1, class2 and class3 power level transmissions without requiring an external PA
- Integrated 32K oscillator for power management

3. Block Diagram



4. General Specification

4.1 2.4GHz RF Specification

Feature	Description	
WLAN Standard	IEEE 802.11 b/g/n/ax Wi-Fi compliant	
Frequency Range	2.400 GHz ~ 2.4835 GHz (2.4 GHz ISM Band)	
Number of Channels	2.4GHz: Ch1 ~ Ch14	
Test Items	Typical Value	EVM
Output Power	802.11b /11Mbps: 19dBm $\pm$ 2 dB	EVM $\leq$ -9dB
	802.11g /54Mbps: 18dBm $\pm$ 2 dB	EVM $\leq$ -25dB
	802.11n /MCS7: 17dBm $\pm$ 2 dB	EVM $\leq$ -28dB
	802.11ax HE20 MCS11: 13dBm $\pm$ 2 dB	EVM $\leq$ -35dB
	802.11ax HE40 MCS11: 13dBm $\pm$ 2 dB	EVM $\leq$ -35dB
Spectrum Mask	Meet with IEEE standard	
Freq. Tolerance	$\pm$ 20ppm	
Test Items	TYP Test Value	Standard Value
SISO Receive Sensitivity (11b,20MHz) @8% PER	- 1Mbps @ -94 dBm	$\leq$ -83 dBm
	- 11Mbps @ -85 dBm	$\leq$ -76 dBm
SISO Receive Sensitivity (11g,20MHz) @10% PER	- 6Mbps @ -90 dBm	$\leq$ -85 dBm
	- 54Mbps @ -71 dBm	$\leq$ -68 dBm
SISO Receive Sensitivity (11n,20MHz) @10% PER	- MCS=0 @ -90 dBm	$\leq$ -85 dBm
	- MCS=7 @ -69 dBm	$\leq$ -67 dBm
SISO Receive Sensitivity (11n ,40MHz) @10% PER	- MCS=0 @ -87 dBm	$\leq$ -82 dBm
	- MCS=7 @ -66 dBm	$\leq$ -64 dBm
SISO Receive Sensitivity (11ax,20MHz) @10% PER	- MCS=0 @ -90 dBm	$\leq$ -74 dBm
	- MCS=11 @ -60 dBm	$\leq$ -52 dBm
SISO Receive Sensitivity (11ax ,40MHz) @10% PER	- MCS=0 @ -87 dBm	$\leq$ -71 dBm
	- MCS=11 @ -57 dBm	$\leq$ -49 dBm
Maximum Input Level	802.11b : -10 dBm	
	802.11g/n : -20 dBm	
Antenna Reference	Small antennas with 0~2 dBi peak gain	

4.2 5GHz RF Specification

Conditions : VBAT=3.3V ; VDDIO=3.3V ; Temp:25°C

Feature	Description	
WLAN Standard	IEEE 802.11a/n/ac/ax 2x2, Wi-Fi compliant	
Frequency Range	5.150 GHz ~ 5.850 GHz (5.0 GHz ISM Band)	
Test Items	Typical Value	EVM
Output Power ²	802.11a /54Mbps: 18 dBm ± 2 dB	EVM ≤ -25dB
	802.11n /MCS7: 17 dBm ± 2 dB	EVM ≤ -28dB
	802.11ac VHT20 MCS8: 16 dBm ± 2 dB	EVM ≤ -30dB
	802.11ac VHT40 MCS9: 15 dBm ± 2 dB	EVM ≤ -32dB
	802.11ac VHT80 MCS9: 15 dBm ± 2 dB	EVM ≤ -32dB
	802.11ax HE20 MCS11: 13 dBm ± 2 dB	EVM ≤ -35dB
	802.11ax HE40 MCS11: 13 dBm ± 2 dB	EVM ≤ -35dB
	802.11ax HE80 MCS11: 13 dBm ± 2 dB	EVM ≤ -35dB
Test Items	Test Value	Standard Value
SISO Receive Sensitivity (11a,20MHz) @10% PER	- 6Mbps @ -90 dBm	≤-85
	- 54Mbps @ -71 dBm	≤-68
SISO Receive Sensitivity (11n,20MHz) @10% PER	- MCS=0 @ -90 dBm	≤-85
	- MCS=7 @ -69 dBm	≤-67
SISO Receive Sensitivity (11n,40MHz) @10% PER	- MCS=0 @ -87 dBm	≤-82
	- MCS=7 @ -66 dBm	≤-64
SISO Receive Sensitivity (11ac,20MHz)@10% PER	- MCS=0, NSS1 @ 90 dBm	≤-82
	- MCS=8, NSS1 @ -64 dBm	≤-60
SISO Receive Sensitivity (11ac,40MHz) @10% PER	- MCS=0, NSS1 @ -87 dBm	≤-79
	- MCS=9, NSS1 @ -59 dBm	≤-55
SISO Receive Sensitivity (11ac,80MHz) @10% PER	- MCS=0, NSS1 @ -84 dBm	≤-79
	- MCS=9, NSS1 @ -56 dBm	≤-54
SISO Receive Sensitivity (11ax,20MHz) @10% PER	- MCS=0 @ -90 dBm	≤-74
	- MCS=11 @ -60 dBm	≤-52
SISO Receive Sensitivity (11ax,40MHz) @10% PER	- MCS=0 @ -87 dBm	≤-71
	- MCS=11 @ -57 dBm	≤-49
SISO Receive Sensitivity (11ax,80MHz) @10% PER	- MCS=0 @ -84 dBm	≤-68
	- MCS=11 @ -54 dBm	≤-46
Maximum Input Level	802.11a/n: -30 dBm	
Antenna Reference	Small antennas with 0~2 dBi peak gain	

4.2 Bluetooth Specification

Feature	Description		
General Specification			
Bluetooth Standard	Bluetooth V5.2 of 1, 2 and 3 Mbps.		
Host Interface	USB		
Antenna Reference	Small antennas with 0~2 dBi peak gain		
Frequency Band	2400 MHz ~ 2483.5 MHz		
Number of Channels	79 channels		
Modulation	GFSK, $\pi/4$ -DQPSK, 8-DPSK		
RF Specification			
	Min(dBm)	Typical(dBm)	Max(dBm)
Output Power		5	
Sensitivity @ BER=0.1% for GFSK (1Mbps)			-70
Sensitivity @ BER=0.01% for $\pi/4$ -DQPSK (2Mbps)			-70
Sensitivity @ BER=0.01% for 8DPSK (3Mbps)			-70
Maximum Input Level	GFSK (1Mbps):-20dBm		
	$\pi/4$ -DQPSK (2Mbps) :-20dBm		
	8DPSK (3Mbps) :-20dBm		

5. ID setting information

WI-FI

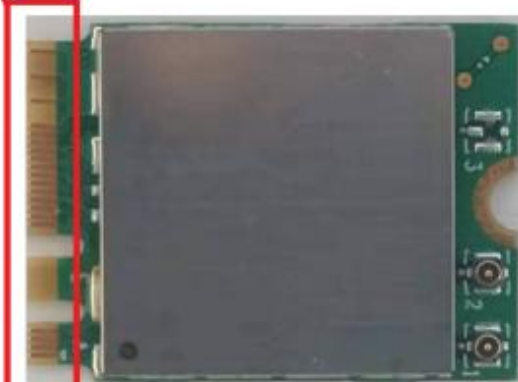
Vendor ID	-
Product ID	-

6. Pin Definition

6.1 Pin Outline

< TOP VIEW >

PIN	Signal	Signal	PIN
74	3_3V	GND10	75
72	3_3V	NC	73
70	NC	NC	71
68	NC	GND9	69
66	NC	NC	67
64	NC	NC	65
62	NC	GND	63
60	NC	NC	61
58	NC	NC	59
56	WL_DIS_N	GND	57
54	BT_DIS_N	PEWAKE0	55
52	PERST0	CLKREQ0	53
50	SUSCLK	GND	51
48	COEX_RXD	REFCLKN0	49
46	COEX_TXD	REFCLKP0	47
44	COEX3	GND	45
42	NC	PETN0	43
40	NC	PETP0	41
38	VENDOR_DEFINED	GND	39
36	NC	PERN0	37
34	NC	PERP0	35
32	NC	GND	33
30	NC	NC	31
28	NC	NC	29
26	NC	NC	27
24	NC	NC	25
22	NC	NC	23
20	NC	NC	21
18	GND	NC	19
16	LED_2#	NC	17
14	NC	NC	15
12	NC	NC	13
10	NC	NC	11
8	NC	NC	9
6	LED_1#	GND	7
4	3_3V	USB_D-	5
2	3_3V	USB_D+	3
		GND	1



6.2 Pin Definition details

NO	Name	Type	Description	Voltage
1	GND	-	Ground connections	
3	USB_D+	I/O	USB differential line for BT	
5	USB_D-	I/O		
7	GND	-	Ground connections	

9	NC	-	Floating (NC)	
11	NC		Floating (NC)	
13	NC		Floating (NC)	
15	NC		Floating (NC)	
17	NC	-	Floating (NC)	
19	NC	-	Floating (NC)	
21	NC	-	Floating (NC)	
23	NC	-	Floating (NC)	
25	NC		Floating (NC)	
27	NC		Floating (NC)	
29	NC		Floating (NC)	
31	NC		Floating (NC)	
33	GND	-	Ground connections	
35	PERP0	I	PCIe RX differential signals	
37	PERN0	I		
39	GND	-	Ground connections	
41	PETP0	O	PCIe TX differential signals	
43	PETN0	O		
45	GND	-	Ground connections	
47	REFCLKP0	I	PCIe clock differential input signal	
49	REFCLKN0	I		
51	GND		Ground connections	
53	CLKREQ0	O	PCIe reference clock request signal, open drain, active low	3.3V
55	PEWAKE0	O	PCIe wake up host, open drain, active low	3.3V
57	GND	-	Ground connections	
59	NC	-	Floating (NC)	
61	NC	-	Floating (NC)	
63	GND	-	Ground connections	
65	NC	-	Floating (NC)	
67	NC	-	Floating (NC)	
69	GND9	-	Ground connections	
71	NC	-	Floating (NC)	
73	NC	-	Floating (NC)	
75	GND10	-	Ground connections	

Bottom side

NO	Name	Type	Description	Voltage
2	3_3V	P	Power supply	3.3V
4	3_3V	P	Power supply	3.3V
6	LED_1#	O	WLAN LED signal	3.3V
8	NC	-	Floating (NC)	
10	NC		Floating (NC)	
12	NC		Floating (NC)	
14	NC		Floating (NC)	
16	LED_2#	O	BT LED signal	3.3V
18	GND	-	Ground connections	
20	NC	-	Floating (NC)	
22	NC	-	Floating (NC)	
24	NC		Floating (NC)	
26	NC		Floating (NC)	
28	NC		Floating (NC)	
30	NC		Floating (NC)	
32	NC		Floating (NC)	
34	NC	-	Floating (NC)	
36	NC	-	Floating (NC)	
38	VENDOR DEFINED	-	Host wake BT. No function, please don't connect to this pin.	
40	NC	-	Floating (NC)	
42	NC	-	Floating (NC)	
44	COEX3	I/O	LTE coexistence signal	3.3V
46	COEX_TXD	O	LTE coexistence signal	3.3V
48	COEX_RXD	I	LTE coexistence signal	3.3V
50	SUSCLK	I	Sleep clock input	3.3V
52	PERST0	I	PCIe reset signal, active low	3.3V
54	BT_DIS_N	I	Bluetooth enable signal, pull low to disable BT function, default high.	3.3V
56	WL_DIS_N	I	WLAN enable signal, pull low to disable BT function, default high.	3.3V
58	NC	-	Floating (NC)	

60	NC	-	Floating (NC)	
62	NC	-	Floating (NC)	
64	NC	-	Floating (NC)	
66	NC	-	Floating (NC)	
68	NC	-	Floating (NC)	
70	NC	-	Floating (NC)	
72	3_3V	P	Power supply	3.3V
74	3_3V	P	Power supply	3.3V

P:POWER I:INPUT O:OUTPUT

7. Electrical Specifications

7.1 Power Supply DC Characteristics

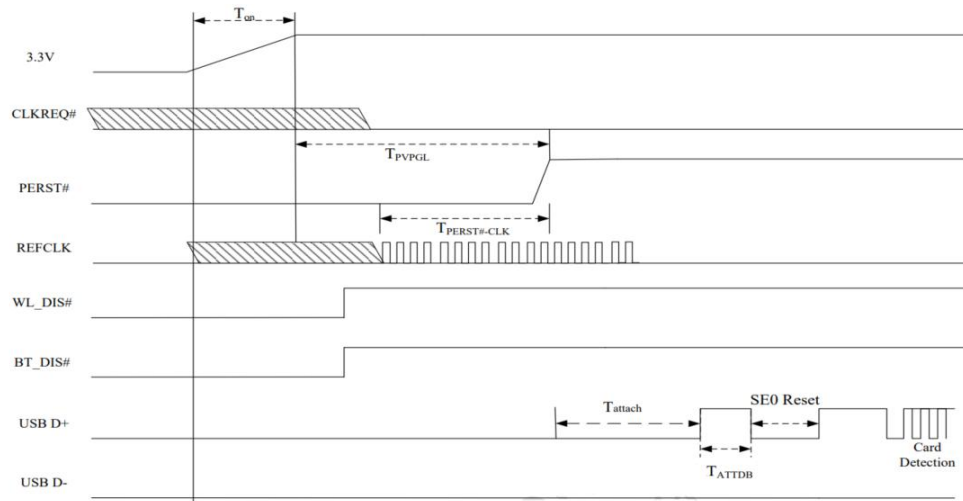
	MIN	TYP	MAX	Unit
Operating Temperature	0	25	70	deg.C
VDD33	3.0	3.3	3.6	V

7.2 Power Consumption

Power Consumption		VDD33 = 3.3V(Unit:mA)
	TX (2.4G 11M)	369
	TX (2.4G 54M)	210
	TX (2.4G 11N)	205
	RX (2.4G 11N)	163
	TX (5G 54M)	210
	TX (5G vHT80)	187
	RX (5G vHT80)	185

7.3 Interface Circuit time series

7.3.1 PCIe Bus during Power On Sequence



T_{on}: The main power ramp up duration

T_{PVPGL}: Power valid to PERST# input inactive

T_{PERST#-CLK}: Reference clock stable before PERST# inactive

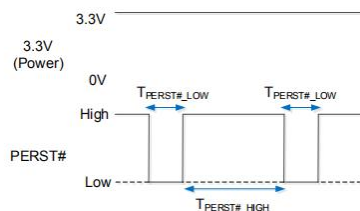
T_{attach}: The interval to turn on BT after PERST# de-asserted

T_{ATTDB}: the debounce interval with a minimal duration of 100ms that provided by the USB system Software

T_{SE0 Reset}: USB host send SE0 Reset duration

Symbol	Unit	Min	Typical	Max
T_{on}	ms	0.5	1.5	5
T_{PVPGL}	ms	Implementation specific; recommended 50ms		
T_{PERST#-CLK}	us	100	--	--
T_{attach}	ms	0.5	2	5
T_{ATTDB}	ms	100	--	--
T_{SE0 Reset}	ms	10	--	--

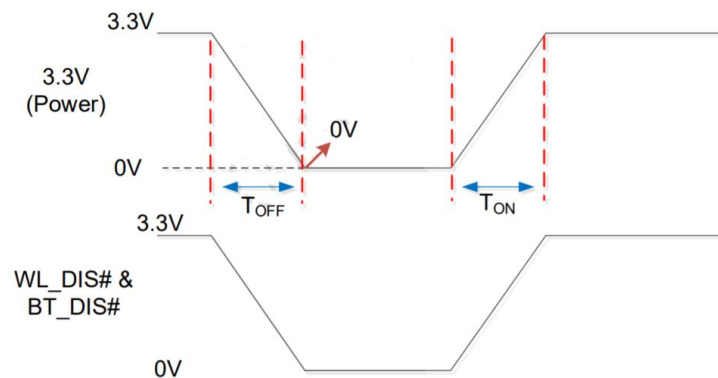
7.3.2 PCIe PERST# Timing Sequence



RTL8821CE-CG PCIe PERST# Timing Parameters

	Min	Typical	Max	Unit	Description
T _{PERST#_LOW}	6	10	X	ms	PERST# low duration
T _{PERST#_HIGH}	400	500	X	ms	PERST# high duration

7.3.3 Power Off Sequence

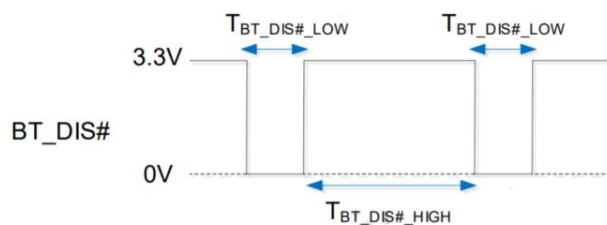


RTL8822CE-CG Power Off Timing Parameters

Symbol	Min	Typical	Max	Unit	Description
T_{OFF}	1.5ms	--	--	ms	Measure point start on 100% Measure point end on 0% (must be 0V)
T_{ON}	0.5	1.5	5	ms	Measure point start on 0% (must be 0V) Measure point end on 100%

Note: If BT_DIS# can't connect to the same power source with 3.3V, it need to be de-asserted before PERST# with 100ms in power on sequence.

7.3.4 BT_DIS Timing Sequence



	Min	Typical	Max	Unit	Description
BT_DIS#_LOW	200	--	--	ms	BT_DIS# low duration
BT_DIS#_HIGH	500	--	--	ms	BT_DIS# high duration

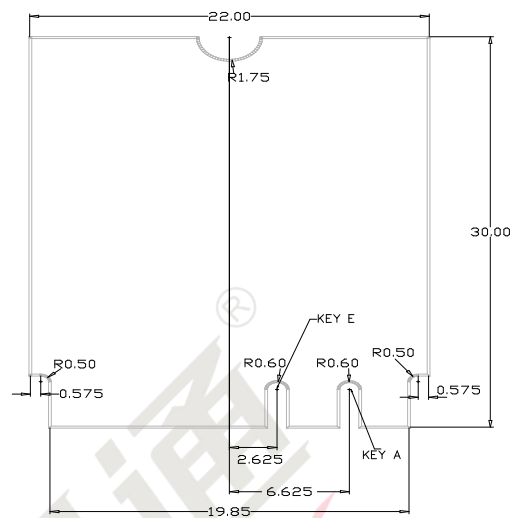
7.3.5 Platform state transitions

3.3V Power range	3.3V Ripple	3.3V Noise	Rise time	
			Min	Max
+/-0.165V	300mVpp @ switching frequency > 100KHz		0.5ms	5ms

8. Size reference

8.1 Module Picture

L x W : 22 x 30 (+0.3/-0.1) mm
FG6252MPUB-00



H: 2.2 (±0.2) mm



Weight

2.6g

8.2 Marking Description

< TOP VIEW >



备注:

二维码内容: 112233445566;FG6252MPUB-00

1. Fn-Link 商标 logo
2. 机型: 6252M-PUB, 不变
3. 芯片: Realtek RTL8852BE, 不变
4. 二维码: 编码规则为 “wifi mac 地址;成品料号”

例如: 112233445566;FG6252MPUB-00 (MAC 地址以实际为准)

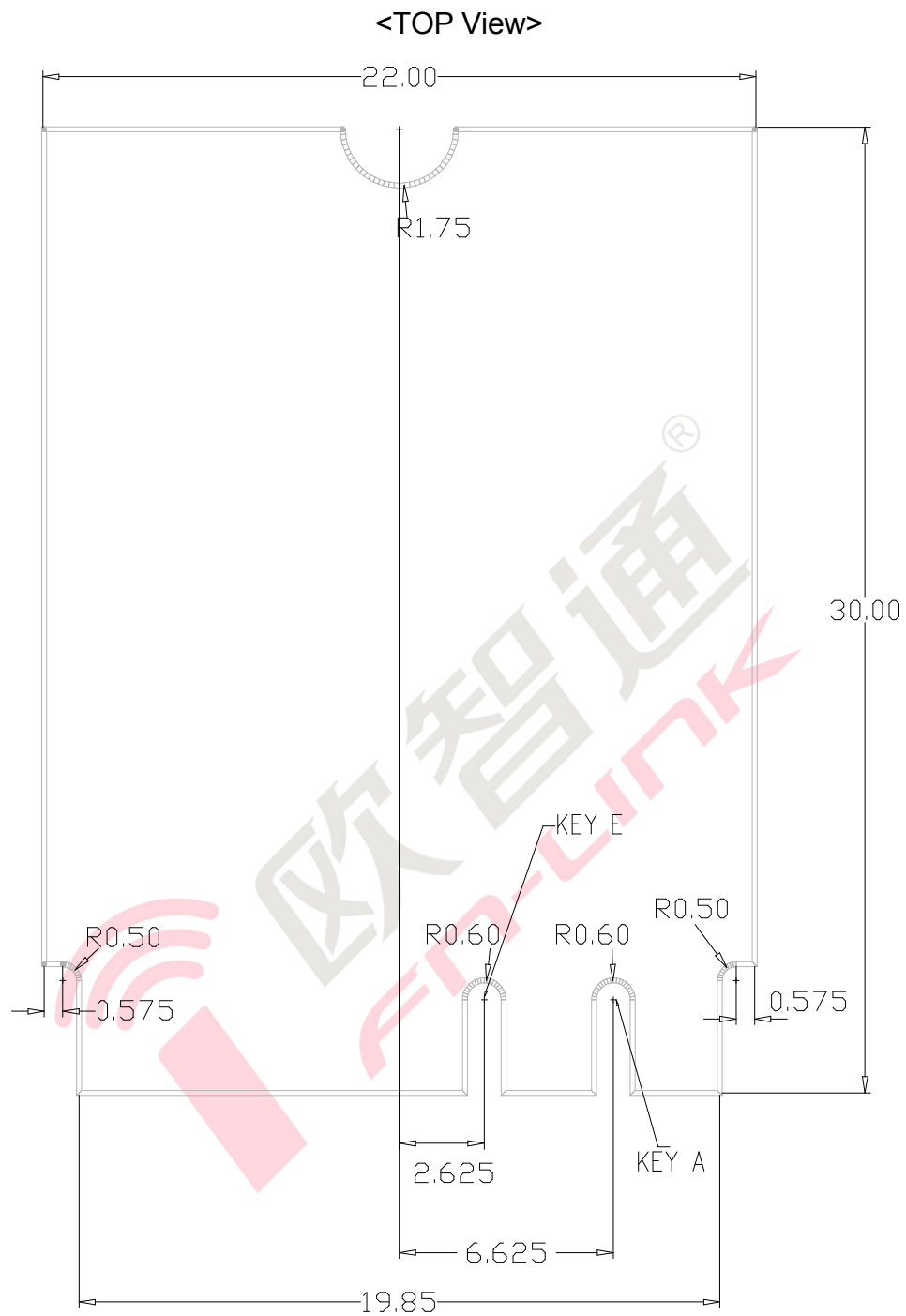
——BT MAC 在 WIFI MAC 基础上+1 (WIFI 地址需跳 1, 不能与 BT 地址重复), 二维码中不显示此内容。

5.V/N 00(V/N 到 00 之间为两个空格, 00 为成品料号后缀, 与二维码右对齐。)

8.3 List of certified information

Certification project	Certificate number
SRRC	CMIIT ID:24J43T230001
FCC	TBD
CE	TBD
IC	TBD
NCC	TBD
KCC	TBD
TELEC	TBD
Brazil	TBD

8.4 Physical Dimensions

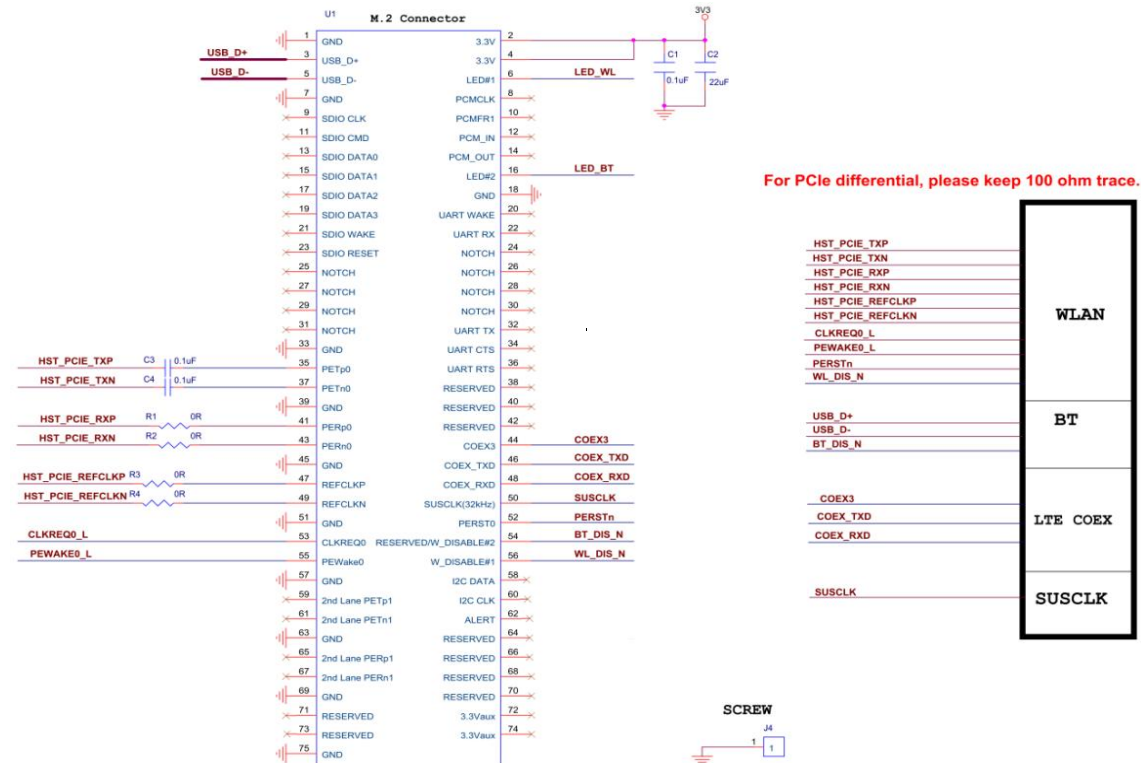


9. The Key Material List

Item	Part Name	Description	Manufacturer
1	PCB	6252M-PUB 22X30X0.8mm TG180	XY-PCB, GDKX, Sunlord, SLPCB, Truly
2	Inductor	2520 2.2UH $\pm 20\%$,	Sunlord, Ceaiya, Cenker
3	Diplexer	1608 Dual-band, dual-mode 2.4GHz/5GHz WLAN	Glead, Walsin, ACX, Murata, MAG.LAYERS, ftrgroup
4	Crystal	3225 40MHz 12pF $\pm 10\text{ppm}$	ECEC, TKD, Hosonic, JWT, TXC
5	Chipset	RTL8852BE-CG	Realtek
6	Shielding	6252M-PUB Shielding cover	Suntech, JLitong
7	ipex	4 代 TA-RF03-001-03-811, CD-ARF004-P01K	创迪尔

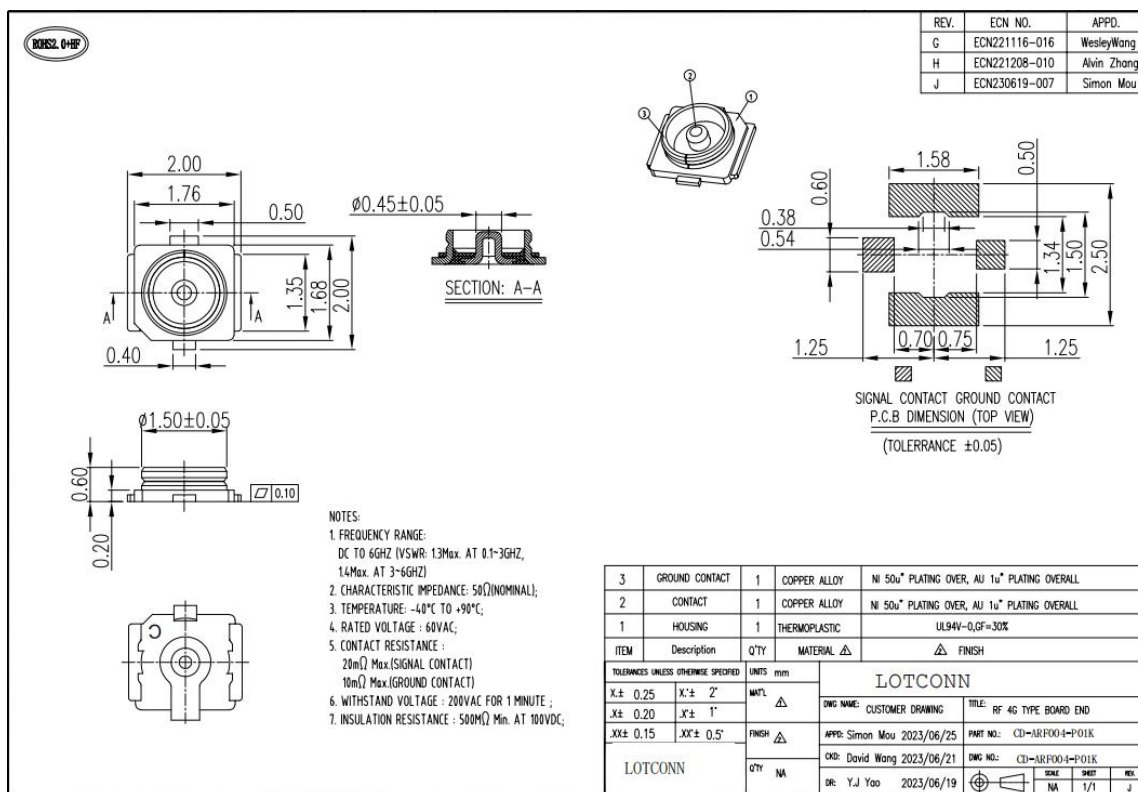
10. Reference Design

10.1 Reference design



- Note:
- Both of the 2 ANT's are all support 2.4G/5G/BT function.
 - 6252M-PUB antenna port is control by driver if diversity function is enabled.
 - C1, C2 placed close to module side.
 - PCIe differential keep 100 ohm trace.
 - USB differential keep 90 ohm trace.

10.2 Connector Specification



11. RoHS compliance

All hardware components are fully compliant with EU RoHS directive

12. Package

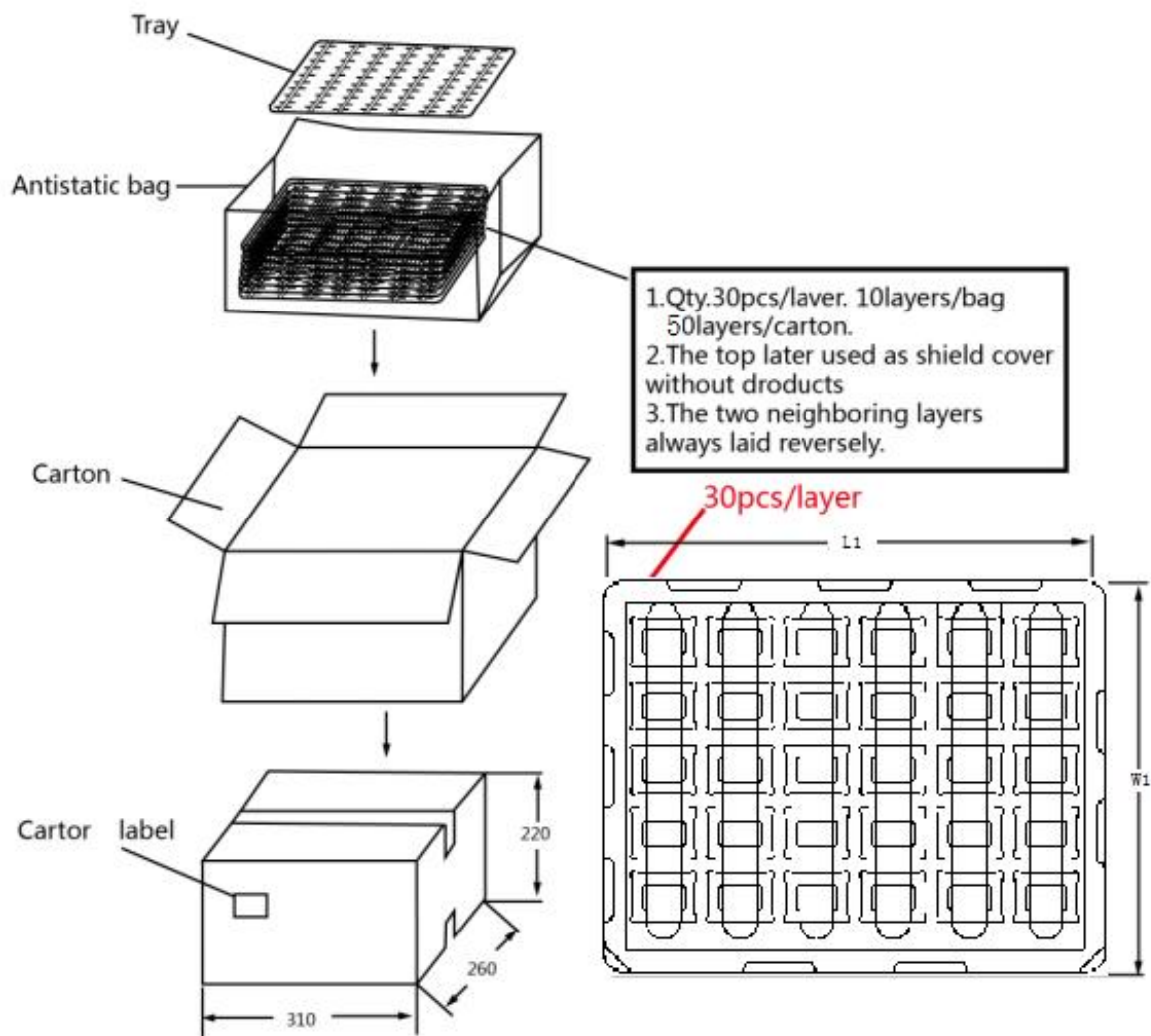
12.1 Tray

Layer size: L250.0*W190.0 mm

Layer material: PVC

Carton size: L310.0*W260.0*H220.0 mm

Carton material: A=A



13. Moisture sensitivity

The Modules is a Moisture Sensitive Device level 3, in according with standard IPC/JEDEC J-STD-020, take care

all the relatives requirements for using this kind of components.

Moreover, the customer has to take care of the following conditions:

- a) Calculated shelf life in sealed bag: 12 months at <40°C and <90% relative humidity (RH)
- b) Environmental condition during the production: 30°C / 60% RH according to IPC/JEDEC J-STD-033A paragraph 5
- c) The maximum time between the opening of the sealed bag and the reflow process must be 168 hours if condition
- d) “IPC/JEDEC J-STD-033A paragraph 5.2” is respected
- e) Baking is required if conditions b) or c) are not respected
- f) Baking is required if the humidity indicator inside the bag indicates 10% RH or more